Resistors

Flameproof Power Metal Film Resistors

MFP Series

- Smallest size for power rating
- Resistance range 0.1 ohms to 1M ohms
- Flameproof protection
- Surface mount ZI-form option

All parts are Pb-free and comply with EU Directive 2011/65/EU amended by (EU) 2015/863 (RoHS3)

Electrical Data

		MFP1	MFP2		
Power rating at 70°C	watts	<1 Ω: 0.7 >=1 Ω: 1.0	2		
Resistance range	ohms	0R1 – 1M	1R0 – 1M		
Limiting element voltage	volts	350			
TCR	ppm/°C	< 1 Ω: 300 1 Ω - 9.1 Ω: 200 ≥10 Ω: 100	100		
Resistance tolerance	%	1, 2, 5			
Standard values		E24 preferred			
Thermal impedance	°C/watt	120	82		
Ambient temperature range	°C	-55 to 155			

Physical Data

Dimensions (mm) & Weight (g)								
Туре	L Max	D Max	f min	d nom	PCB mounting centres	Min. bend radius	Wt.nom	
MFP1	6.2	2.5	21.0	0.6	10.2	0.6	0.3	D
MFP2	10.0	4.0	27.0	0.8	18.4	1.2	0.55	

Construction

The resistance element is a precisely controlled thin film of metal alloy on a high purity ceramic core, protected by a cement coating applied so that terminations remain completely clear. This permits a well defined body length (clean lead to clean lead dimension L).

Terminations

Material Solder-coated copper wire.

- StrengthThe terminations meet the requirements of
IEC 68.2.21
- **Solderability** The terminations meet the requirements of IEC 115-1, Clause 4.17.3.2

Marking

Resistors are colour coded with 4 or 5 bands depending on value and tolerance. IEC 62 colours are used.

Solvent Resistance

The body protection and marking are resistant to all normal industrial cleaning solvents suitable for printed circuits.

Flammability

The resistor coating will not burn or emit incandescent particles under any condition of applied temperature or power overload.

General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print. BI Technologies IRC Welwyn







MFP Series

Performance Data

		Maximum
Load at rated power : 1000 hours at 70°C	ΔR %	5
Shelf life : 12 months at room temperature	ΔR %	2
Derating from rated power at 70°C	ΔR %	zero at 155°C
Climatic	ΔR %	3
Climatic category		50/155/56
Temperature rapid change	ΔR %	0.5
Resistance to solder heat	ΔR %	0.5
Voltage proof	volts	500 min

Application Notes

- 1. If the resistors are to dissipate full rated power, it is recommended that the terminations should not be soldered closer than 4mm from the body.
- 2. Due to operating temperature limitations imposed by some pcb materials, derating may be necessary. An estimate of the temperature rise to be expected can be calculated using the thermal impedance figures given under Electrical Data.

Packaging

MFP resistors are normally supplied tape packed ready for loading onto automatic sequencing and insertion machines.

The standard taping method and critical dimensions are shown in Figure 1.

Component wires will not protrude beyond the outside edge of the tapes.

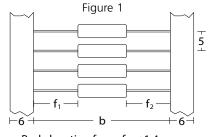
Alternative packaging available by request.

3. MFP2 resistors can also be supplied loose packed with radial, goalpost or lancet pre-formed leads- see https://www.ttelectronics.com/TTElectronics/media/ProductFiles/Resistors/ApplicationNotes/TN008-resistors-Leadform-Capability.pdf, or in ZI-form SMD format packed in blister tape- see https://www.ttelectronics.com/TTElectronics/media/ProductFiles/Resistors/Datasheets/ZI-form.pdf

68

Туре	MFP1	MFP2

52



Body location f $_1 - f_2 \le 1.4 \text{ mm}$

General Note

b (mm)

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.

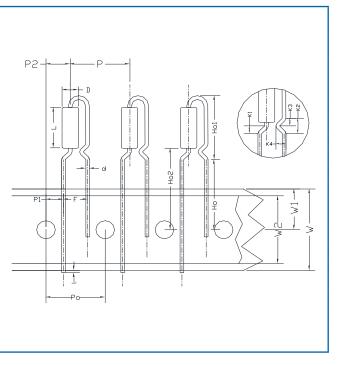
BI Technologies IRC Welwyn



MFP Series

Also a 2W radial taped version is available as shown below

MFP2R Radial Taped Dimensions (mm)							
Dimension	Notation	Nominal	Tolerance				
Component Body Length	L	10.0 Max					
Component Body Diameter	D	4.0 Max					
Terminal Lead Diameter	d	0.8 Nom					
Component Pitch	Р	12.7	±0.5				
Pitch of Holes	Ро	12.7	±0.2				
Distance between Hele & Component	P1	3.85	±0.3				
Distance between Hole & Component	P2	5.85	±0.5				
Lead Pitch	F	5.0	+0.75 -0.34				
Width of Backing Strip	W	18.0	±0.3				
Position of Hole	W1	9.0	±0.25				
Diameter of Hole	Do	4.0	±0.3				
Height to Lead Form	Но	16.0	±0.3				
Height from Lead Form	Ho1	21.7 Max					
Height to Resistor	Ho2	18.0 Max					
Width of Adhesive Tape	W2	15.0	±0.5				
Length of protrusion	I.	<2.5					
	K1	2.0	±0.3				
Form Dimensions	К2	3.0	±0.5				
	К3	1.5	±0.25				
	К4	1.0	±0.2				



Ordering Procedure

Example: MFP2-4K7FI (MFP2, 4.7 kilohms ±1%, Pb-free)

M F P 2		4 K 7	F	
1	2	3	4	5

1	2	3	4	5			
Туре	Leadforming	Value	Tolerance	Packing			
MFP1	Blank = Axial	3/4 characters	F = ±1%		MFP1	Ammo	5000/box
MFP2	R = Radial taped	R = ohms	G = ±2%	1	MFP2	Ammo	2000/box
	(MFP2 only)	K = kilohms	J = ±5%	T15	MFP2R	Reel	1500/reel
		M = megohms					

General Note

TT Electronics reserves the right to make changes in product specification without notice or liability. All information is subject to TT Electronics' own data and is considered accurate at time of going to print.